The 5th International Congress on 3D Materials Science 2021

June 29–July 2, 2021
Hyatt Regency Washington on Capitol Hill,
Washington, D.C., USA

SUBMIT AN ABSTRACT BY OCTOBER 30, 2020

Participate in the premier forum for 3D Materials Science by presenting at the 5th International Congress on 3D Materials Science (3DMS 2021).

The congress program includes, but is not limited to, the following technical topics:

- Methods for materials simulation, modeling, and characterization in 3D
- 3D data processing and reconstruction algorithms
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D
- Machine learning
- New characterization methods

3DMS 2021 distills the most current knowledge of the field in a four-day learning and networking experience. Don’t miss your opportunity to contribute. Submissions will be considered for a topical collection of the TMS journal Integrating Materials and Manufacturing Innovation dedicated to the meeting. For more details and to submit your abstract, visit: www.tms.org/3DMS2021

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